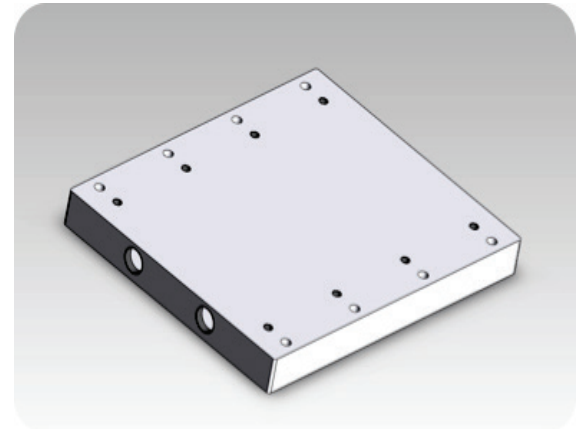
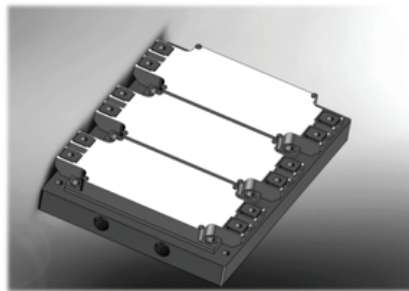


Standard Liquid Cold Plates

Baknor The Way To Cool

Part Number	Size	Weight	Efficiency
BK CP1421	140 x 210 x 18.5 mm	1.3 kg	(Rth = 10° C/kw @ 51/min)
BK CP1426	140 x 260 x 18.5 mm	1.6 kg	(Rth = 8 °C/kw @ 51/min)
BP CP1518	150 x 180 x 18.5 mm	1.1 kg	(Rth = 10 °C/kw @ 51/min)
BP CP1521	150 x 210 x 18.5 mm	1.35 kg	(Rth = 10 °C/kw @ 51/min)



Other Baknor Products Thermal Solutions

Natural Convection

BGA Cooling
Heat Sinks–Extrusion
Heat Sinks–Castings
Heat Sinks–Machining

Force Convection

Fan Assemblies
Fin Assemblies

Phase Change Cooling

Heat Pipes
Vapor Chambers

Liquid Cooling

Brazed
Serpentine Pipe

Thermal Assemblies

Part Number

Compatible Power Module Packages

BK CP1421

Fuji Semiconductor M127; M234; M235
Infineon 62mm Package
Microsemi SP6, D3 and D4 Packages
Mitsubishi 62mm Package
Semikron SemiTrans® Case D56

BK CP1426

Fuji Semiconductor M238 & M247
Mitsubishi IGBTMOD™ A, NF & NFH Series

BP CP1518

Fuji Semiconductor M629
Infineon EconoPACK™ +
Mitsubishi Intellimod™ L Series
Semikron SEMIX® 33

BP CP1521

Fuji 122 X 62MM Package
Infineon EconoDUAL™ 3
Mitsubishi IGBTMOD™ A & NX SERIES
Semikron SEMIX® 3

baknor
Thermal and Packaging



Standard Liquid Cold Plate

Baknor

The Way To Cool

Standard Brazed Liquid Cold Plate

Part Number: BK CP1421

Compact

(140 x 210 x 18.5 mm)

Light

(1.3 kg)

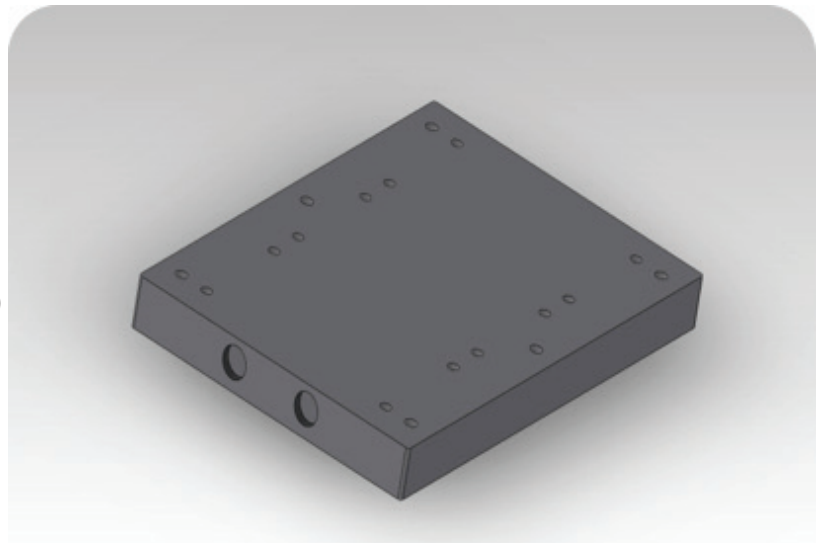
Efficient

(Rth = 10° C/kw @ 51/min)

Safe & Reliable

Leak Free

(100% tested @ 10 bar)



Materials:

Aluminium Alloy AL EN AW 6060+

Turbulators Inside

Cooling Circuit 100% Sealed By Brazing Under Controlled Atmosphere

Very Uniform Temperature Distribution Under Power Modules

Suitable For Any High Power
Semiconductor Application



Compatible Power Module Packages

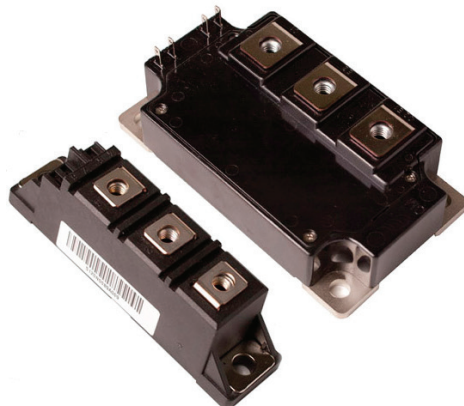
Mitsubishi 62mm Package

Infineon 62mm Package

Semikron SemiTrans® Case D56

Fuji Semiconductor M127; M234; M235

Microsemi SP6, D3 and D4 Packages



baknor
Thermal and Packaging

Other Baknor Products Thermal Solutions

Natural Convection

BGA Cooling
Heat Sinks—Extrusion
Heat Sinks—Castings
Heat Sinks—Machining

Force Convection

Fan Assemblies
Fin Assemblies

Phase Change Cooling

Heat Pipes
Vapor Chambers

Liquid Cooling

Brazed
Serpentine Pipe

Thermal Assemblies

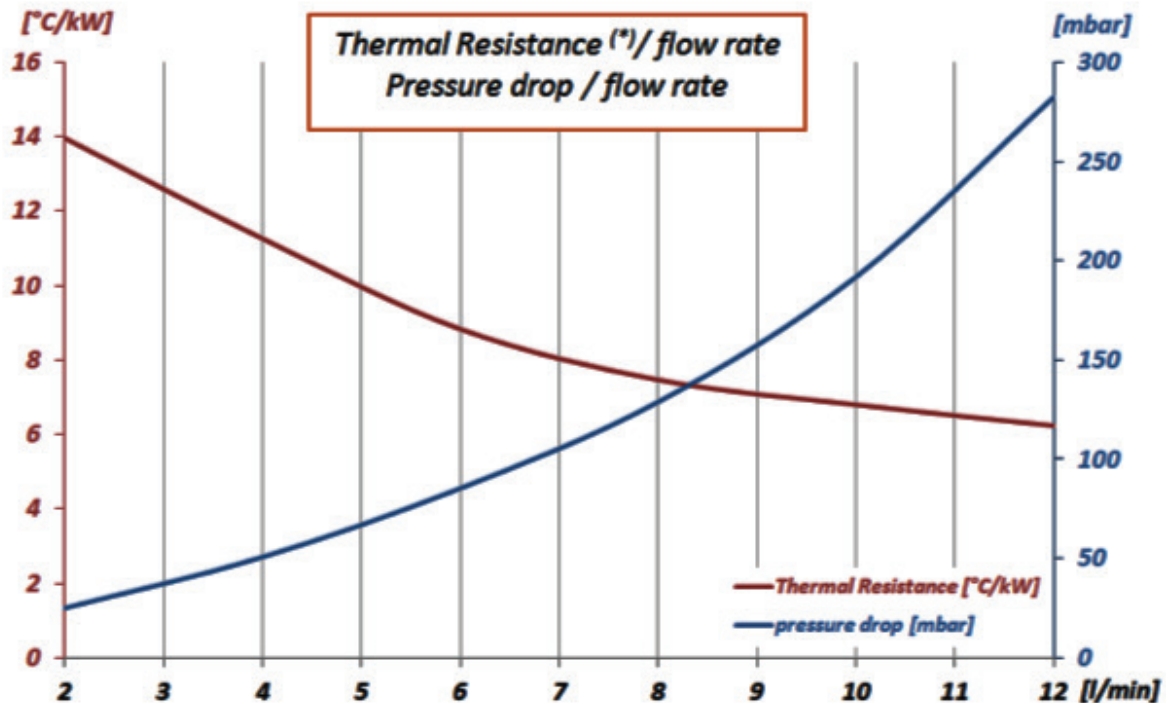
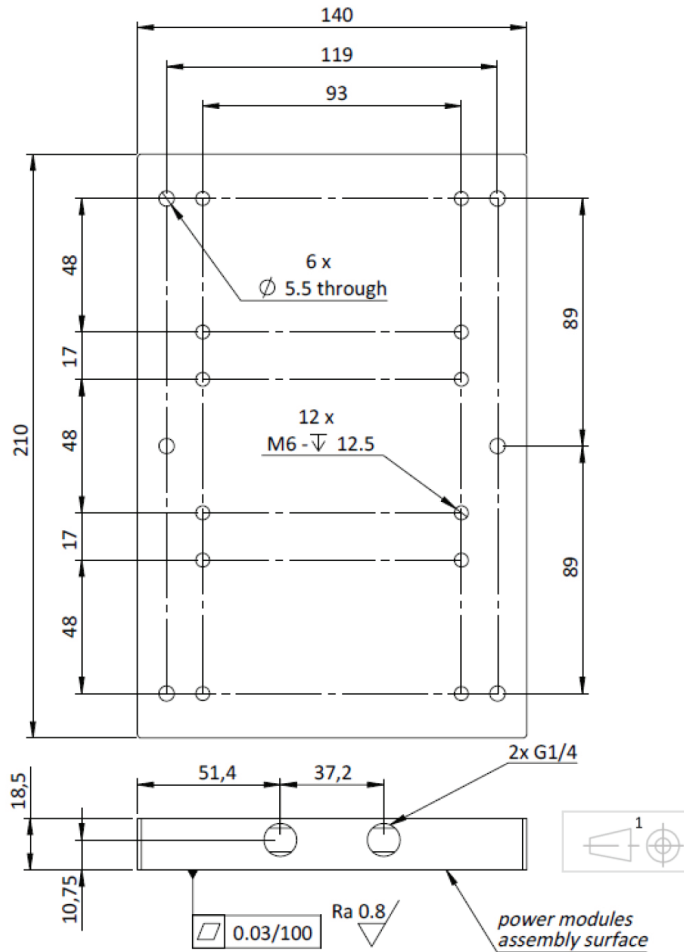
Other Baknor Products
Packaging Solutions

Machining
Precision
Repeatable
Complex

Die Casting
High Quality
Aluminium
Zinc
Magnesium

Fabricated Extrusion
Standard Profiles
Custom Profiles
Complete Finishing

Stamped and Formed
Blanking
Deep Drawing
Metal Coining
Progressive Die Stamping



(*) Thermal Resistance: max TLCP surface to T fluid IN
(Water + Ethylene Glycol 50%vol. @40°C)



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Mississauga, Ontario
Canada L4W 4Y8
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1-877-902-2566

sales@baknor.com
www.baknorthermal.com

Standard Liquid Cold Plate

Baknor

The Way To Cool

Standard Brazed Liquid Cold Plate

Part Number: BK CP1426

Compact

(140 x 260 x 18.5 mm)

Light

(1.6 kg)

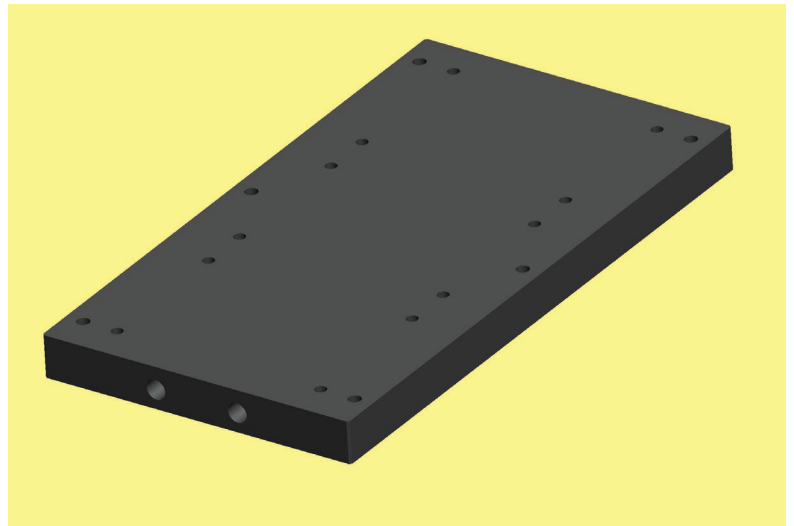
Efficient

(Rth = 8 °C/kw @ 5l/min)

Safe & Reliable

Leak Free

(100% tested @ 10 bar)



Materials:

Aluminium Alloy AL EN AW 6060+

Turbulators Inside

Cooling Circuit 100% Sealed By Brazing Under Controlled Atmosphere

Very Uniform Temperature Distribution Under Power Modules

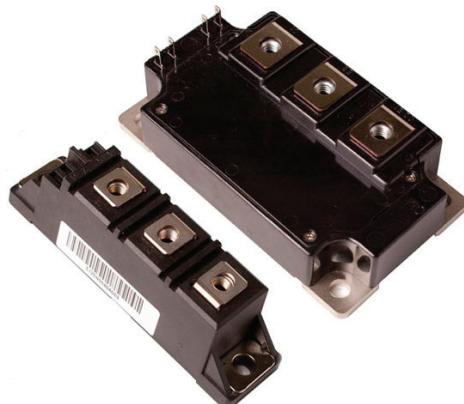
Suitable For Any High Power
Semiconductor Application



Compatible Power Module Packages

Mitsubishi IGBTMOD™
A, NF & NFH Series

Fuji Semiconductor
M238 & M247



Other Baknor Products Thermal Solutions

Natural Convection

BGA Cooling
Heat Sinks—Extrusion
Heat Sinks—Castings
Heat Sinks—Machining

Force Convection

Fan Assemblies
Fin Assemblies

Phase Change Cooling

Heat Pipes
Vapor Chambers

Liquid Cooling

Brazed
Serpentine Pipe

Thermal Assemblies

baknor
Thermal and Packaging

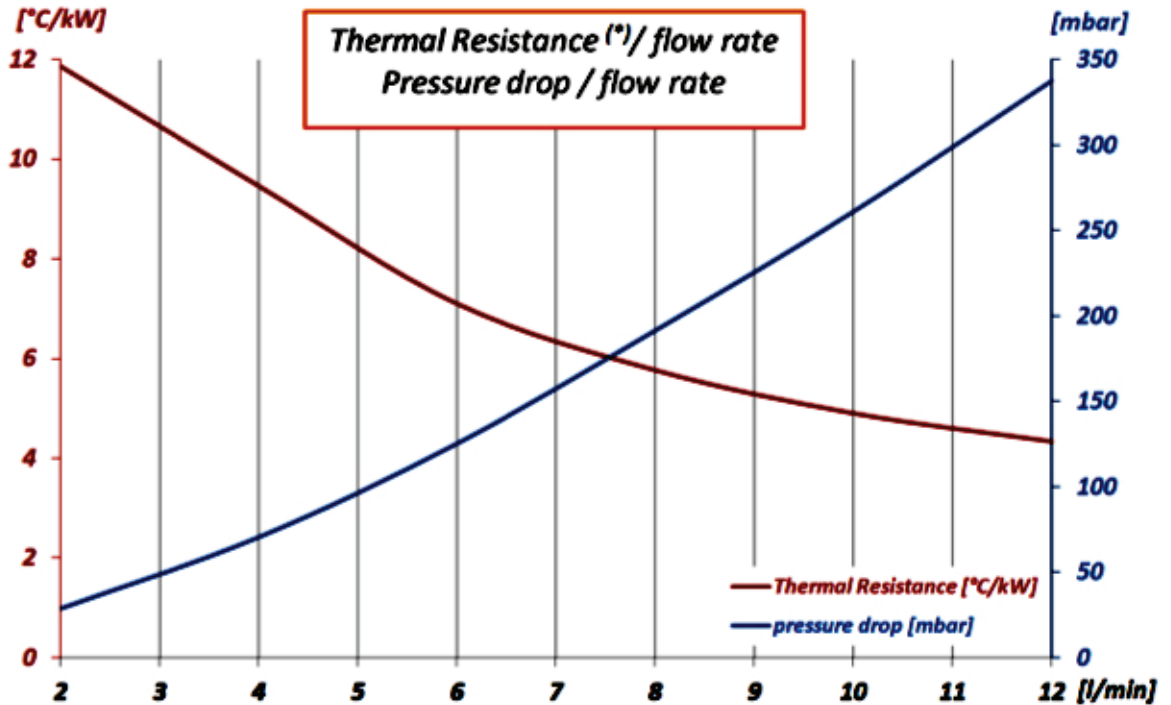
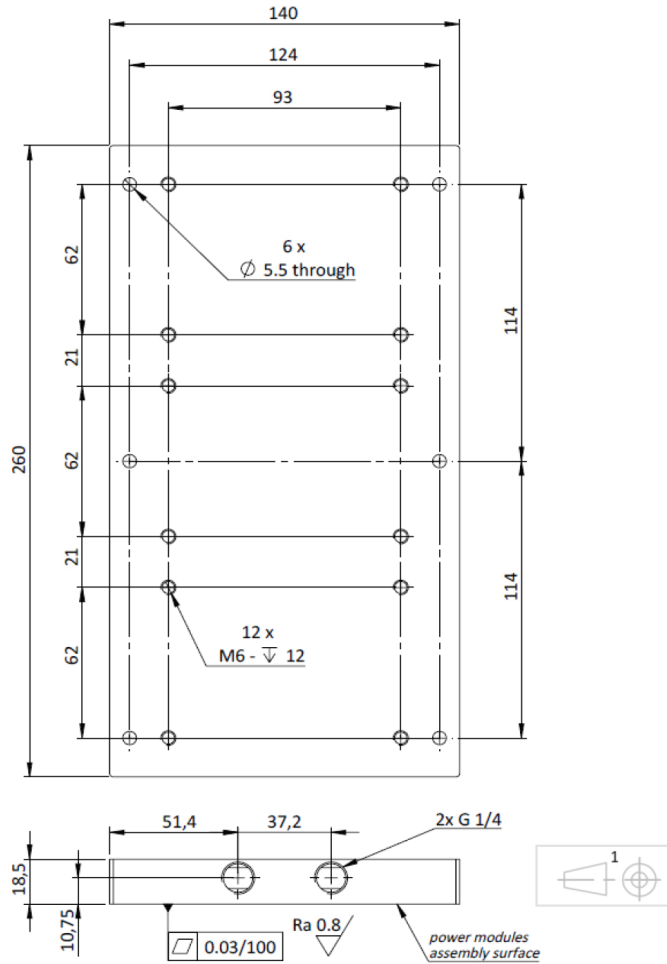
Other Baknor Products
Packaging Solutions

Machining
Precision
Repeatable
Complex

Die Casting
High Quality
Aluminium
Zinc
Magnesium

Fabricated Extrusion
Standard Profiles
Custom Profiles
Complete Finishing

Stamped and Formed
Blanking
Deep Drawing
Metal Coining
Progressive Die Stamping



(*) Thermal Resistance: max TLCP surface to T fluid IN
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www.baknorthermal.com

Standard Liquid Cold Plate

Baknor

The Way To Cool

Standard Brazed Liquid Cold Plate

Part Number: BK CP1518

Compact

(150 x 180 x 18.5 mm)

Light

(1.1 kg)

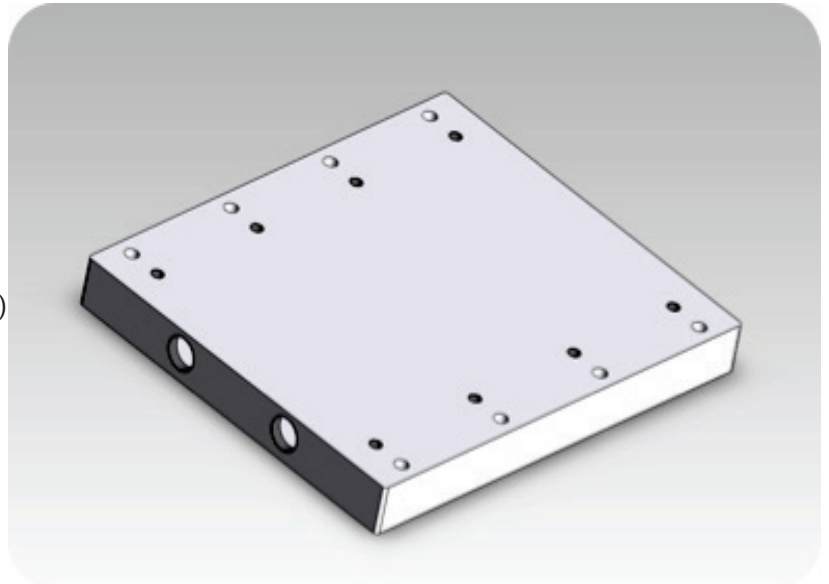
Efficient

($R_{th} = 10 \text{ }^\circ\text{C/kw @ 5l/min}$)

Safe & Reliable

Leak Free

(100% tested @ 10 bar)



Materials:

Aluminium Alloy AL EN AW 6060+

Turbulators Inside

Cooling Circuit 100% Sealed By Brazing Under Controlled Atmosphere

Very Uniform Temperature Distribution Under Power Modules

Suitable For Any High Power
Semiconductor Application



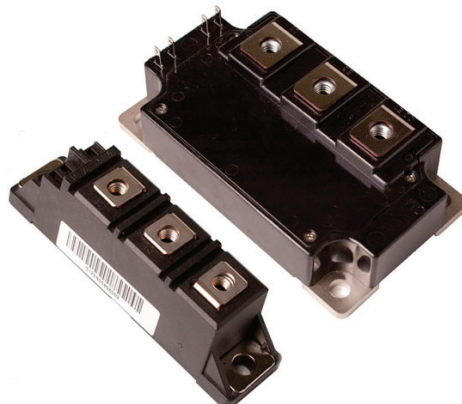
Compatible Power Module Packages

Mitsubishi Intellimod™L Series

Infineon EconoPACK™ +

Semikron SEMIX® 33

Fuji Semiconductor M629



Other Baknor Products Thermal Solutions

Natural Convection

BGA Cooling
Heat Sinks—Extrusion
Heat Sinks—Castings
Heat Sinks—Machining

Force Convection

Fan Assemblies
Fin Assemblies

Phase Change Cooling

Heat Pipes
Vapor Chambers

Liquid Cooling

Brazed
Serpentine Pipe

Thermal Assemblies

baknor
Thermal and Packaging

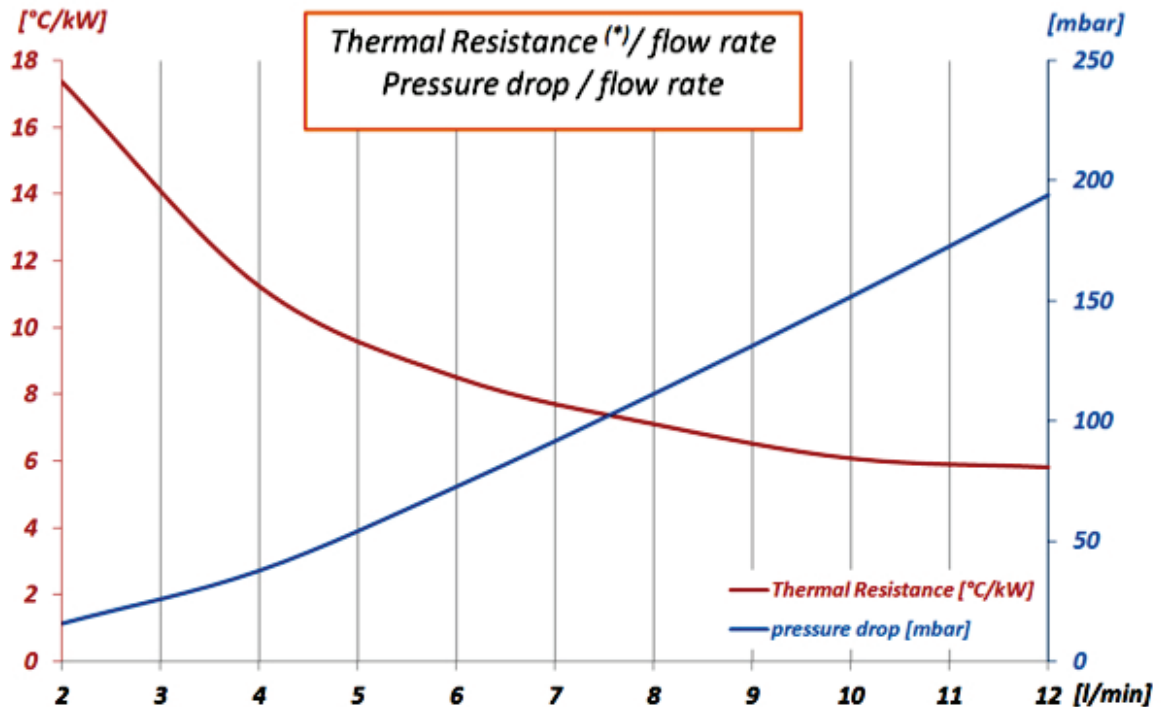
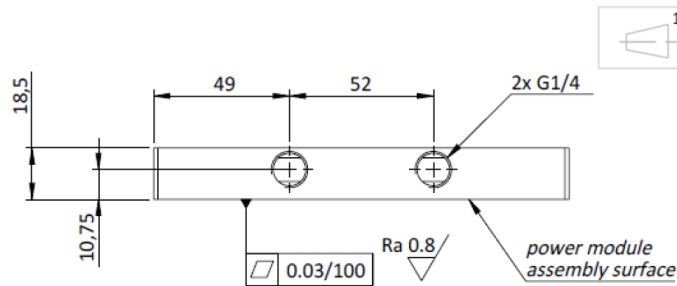
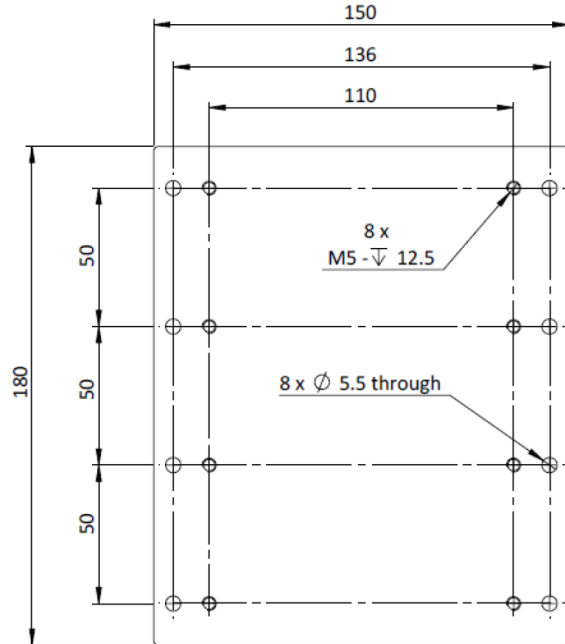
Other Baknor Products
Packaging Solutions

Machining
Precision
Repeatable
Complex

Die Casting
High Quality
Aluminium
Zinc
Magnesium

Fabricated Extrusion
Standard Profiles
Custom Profiles
Complete Finishing

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www.baknorthermal.com

Standard Liquid Cold Plate

Baknor

The Way To Cool

Standard Brazed Liquid Cold Plate

Part Number: BK CP1521

Compact

(150 x 210 x 18.5 mm)

Light

(1.35 kg)

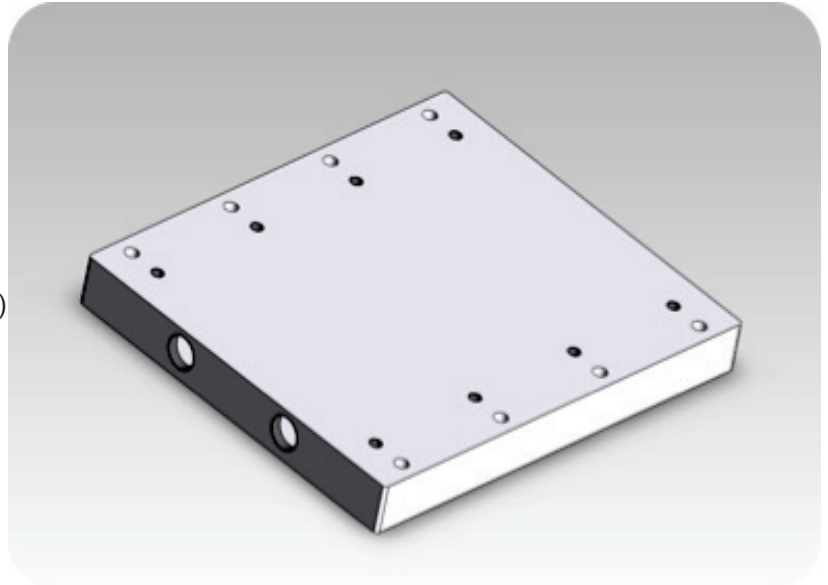
Efficient

(Rth = 10 °C/kw @ 5l/min)

Safe & Reliable

Leak Free

(100% tested @ 10 bar)



Materials:

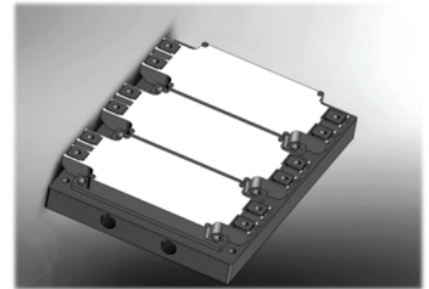
Aluminium Alloy AL EN AW 6060+

Turbulators Inside

Cooling Circuit 100% Sealed By Brazing Under Controlled Atmosphere

Very Uniform Temperature Distribution Under Power Modules

Suitable For Any High Power
Semiconductor Application



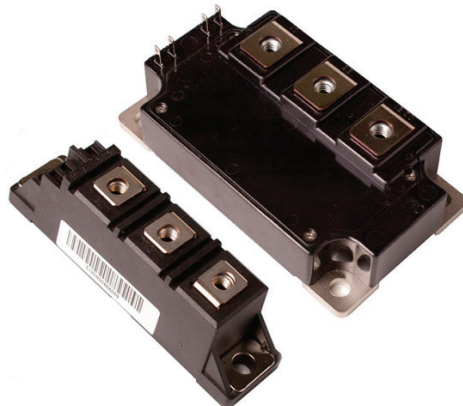
Compatible Power Module Packages

Mitsubishi IGBTMOD™
A & NX SERIES

Infineon EconoDUAL™ 3

Semikron SEMIX® 3

Fuji 122 X 62MM Package



Other Baknor Products Thermal Solutions

Natural Convection

BGA Cooling
Heat Sinks—Extrusion
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Heat Sinks—Machining

Force Convection

Fan Assemblies
Fin Assemblies

Phase Change Cooling

Heat Pipes
Vapor Chambers

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Brazed
Serpentine Pipe

Thermal Assemblies

baknor
Thermal and Packaging

Other Baknor Products
Packaging Solutions

Machining

- Precision
- Repeatable
- Complex

Die Casting

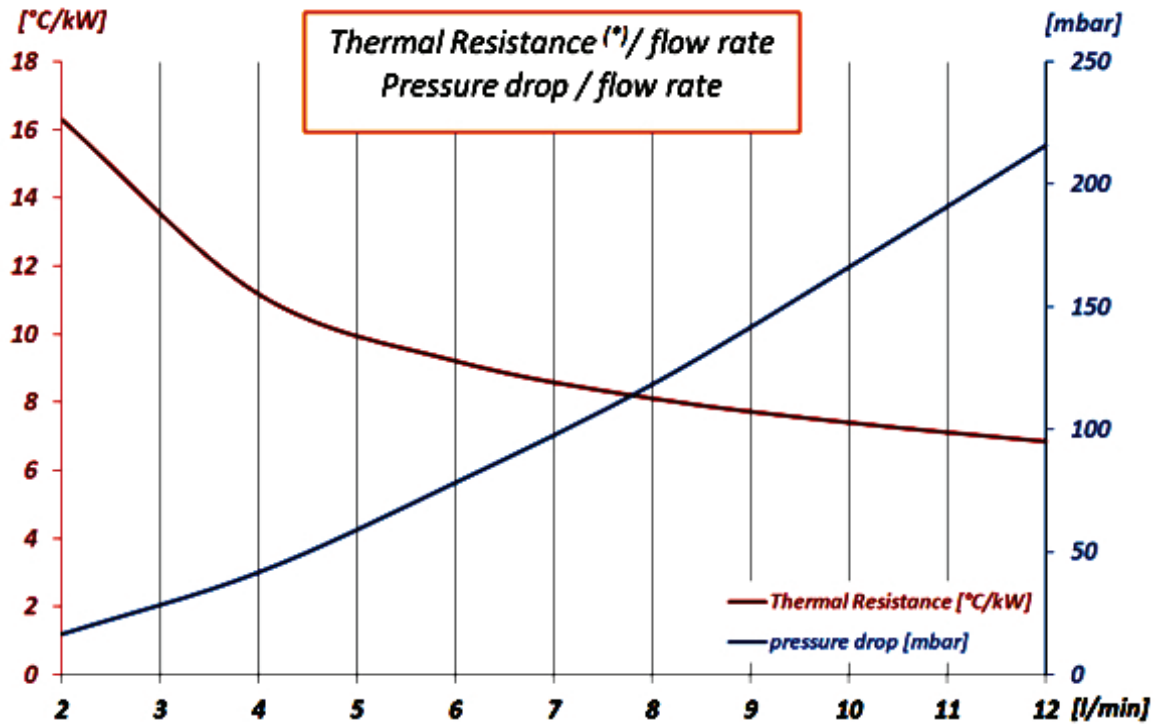
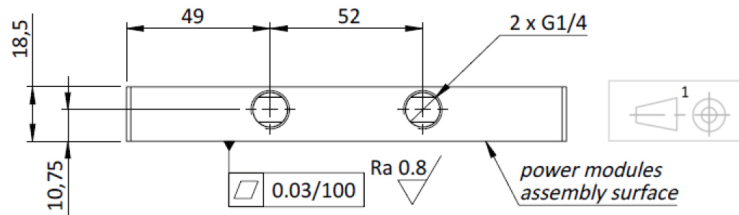
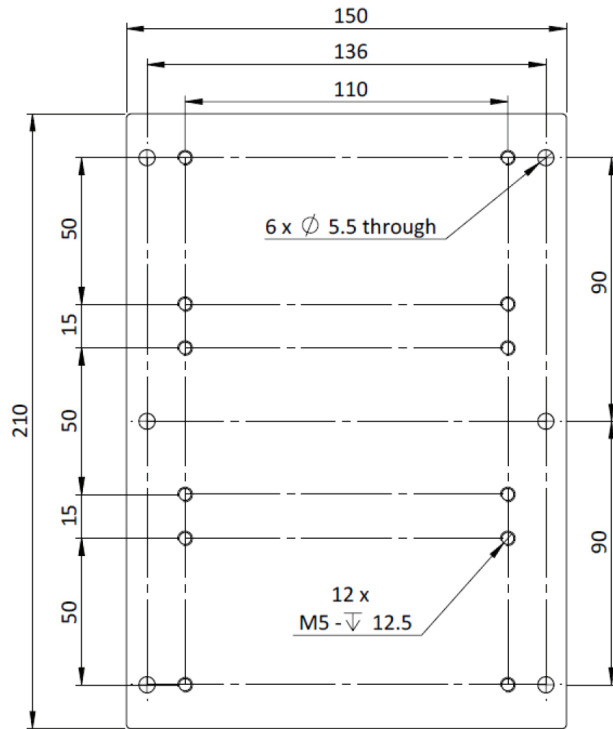
- High Quality
- Aluminium
- Zinc
- Magnesium

Fabricated Extrusion

- Standard Profiles
- Custom Profiles
- Complete Finishing

Stamped and Formed

- Blanking
- Deep Drawing
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- Progressive Die Stamping



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